



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Takasu et al.

Examiner:

Unassigned

Serial No.:

10/603,511

Group Art Unit:

1752

Confirmation No:

3638

Docket:

105-86 PCT/US

Filed:

June 25, 2003

Dated:

February 12, 2004

For:

NEGATIVE RESIST COMPOSITION

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Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

I hereby certify this correspondence is being deposited with the United States Postal Service as first class mail, postpaid in an envelope, addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia

22313-1450 on February 12, 2004

Signed:

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

In order to fulfill the requirements of candor and good faith set forth in 37 C.F.R. §1.56, Applicants submit herewith the following Supplemental Information Disclosure Statement in accordance with the provisions of 37 C.F.R. §1.97 and §1.98.

UNITED STATES PUBLISHED APPLICATIONS

APPLICANT

PUBLICATION NO.

PUBLICATION DATE

Hada et al.

2001/0049073

December 6, 2001

FOREIGN PATENT DOCUMENTS

<u>COUNTRY</u> <u>PUBLICATION NO.</u> <u>PUBLICATION DATE</u>

Japan JP 11-109627

April 23, 1999

Japan

JP 2000-56459

February 25, 2000

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COUNTRY	PUBLICATION NO.	PUBLICATION DATE
Japan	JP 2000-206694	July 28, 2000
Japan	JP 2002-090998	March 27, 2002
Japan	JP 2003-005370	January 8, 2003
Japan	JP 2003-195502	July 9, 2003

Copies of the references set forth above have been enclosed herewith for the convenience of the Examiner and a separate listing of the same has been set forth on Form PTO-1449 also enclosed herewith.

The above-listed references have been cited in an International Search Report issued in a corresponding PCT Patent Application. Accordingly, a copy of the International Search Report showing the degree of relevancy of each of the references is also enclosed. Note that JP 2001-174993, cited in the International Search Report was already cited in the Applicant's prior Information Disclosure Statement. Accordingly, a copy of this reference is not enclosed.

The Supplemental Information Disclosure Statement is being filed before the mailing date of a first Office Action. Accordingly, it is believed that no fee is due.

Serial No.: 10/603,511 Filing Date: June 25, 2003 Docket: 105-86 PCT/US

If the Examiner has any questions or comments relating to the present application, he or she is respectfully invited to contact Applicants' attorney at the telephone number set forth below.

Respectfully submitted,

Steven T. Zuschlag

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FORM TO-1449 . 0.S. DEPARTMENT OF COMMERCE (Rev. 2-32-00-44) ATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

ATTY. DOCKET NO.	SERIAL NO.
105-86 PCT/US	10/603,511
APPLICANT	CONFIRMATION NO.
Takasu et al.	3638
FILING DATE	GROUP
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U	U.S. PATENT PUBLICATIONS							
	DATE	NAME	CLASS	SUB CLASS				

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	2001/0049073	12/06/01	Hada et al.			

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	I I I I I I I I I I I I I I I I I I I		CLASS SUB CLASS		FILING DATE IF APPROPRIATE		

FOREIGN PATENT DOCUMENTS

EXAMINER		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION	
INITIAL							YES	NO
		JP 11-109627	04/23/99	Japan				
		JP 2000-56459	02/25/00	Japan				
		JP 2000-206694	07/28/00	Japan				,
		JP 2002-090998	03/27/02	Japan				
		JP 2003-005370	01/08/03	Japan				
		JP 2003-195502	07/09/03	Japan				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pa	ages, Etc.)
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EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication with applicant.